

PEREGRINE MATERIAL DECLARATION FORM

Product:	PE29101
Ordering Codes:	PE29101A-G, PE29101A-X, PE29101A-Z
Description:	UltraCMOS® High-speed FET Driver, 40 MHz
Package:	Flip Chip
Environmental Compliance	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	Solder Bump
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	2.668547	97.03%	970,279.71
Die	Aluminum	7429-90-5	0.008117	0.30%	2,951.37
Die	Silicon	7440-21-3	0.000541	0.02%	196.76
Die	Arsenic	7440-38-2	0.000003	0.00%	0.98
Die	Boron	7440-42-8	0.000003	0.00%	0.98
Die	Phosphorus	7723-14-0	0.000011	0.00%	3.94
Die	Titanium	7440-32-6	0.001353	0.05%	491.90
Die	Tungsten	7440-33-7	0.027057	0.98%	9,837.91
Die	Cobalt	7440-48-4	0.000054	0.00%	19.68
Die	Copper	7440-50-8	0.000022	0.00%	7.87
Solder Bump	Tin	7440-31-5	0.042116	1.53%	15,313.48
Solder Bump	Silver	7440-22-4	0.001544	0.06%	561.23
Solder Bump	Copper	7440-50-8	0.000441	0.02%	160.35
Solder Bump	Benzocyclobutene	694-87-1	0.000011	0.00%	4.11
UBM	Aluminum	7429-90-5	0.000095	0.00%	34.65
UBM	Nickel	7440-02-0	0.000007	0.00%	2.69
UBM	Vanadium	7440-62-2	0.000101	0.00%	36.70
UBM	Copper	7440-50-8	0.000263	0.01%	95.70
Total Weight (mg)			2.750286	100.00%	1,000,000